

ABSTRACT

Disclosed is a connection component material that can be used, for example, for electrical contact components, such as connectors, lead frames, and harness plugs, used in electrical devices, electronic devices, etc. The connection component material comprises a Cu plating layer formed on a surface of a stainless steel plate, and a Sn plating layer formed on the Cu plating layer, the connection component material being characterized in that: the amount of adhesion of the Cu plating layer is from 1.5 to 45 g/m²; the amount of adhesion of the Sn plating layer is from 1.5 to 15 g/m²; and the surface hardness of the stainless steel plate is from 200 to 400 HV.